

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re PATENT application of )  
Nobuo AOI )  
Serial No. 09/809,043 )  
Filed: March 16, 2001 )  
For: INTERLAYER DIELECTRIC )  
FILM, AND METHOD FOR )  
FORMING THE SAME AND )  
INTERCONNECTION )

Attention: Applications Branch

CERTIFICATE OF MAILING

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PRELIMINARY AMENDMENT

Honorable Commissioner of Patents and Trademarks  
Washington, D.C. 20231

Sir:

Please preliminary amend the subject application as follows:

In the Specification:

Please amend the specification as follows:

Page 19, Line 11

91 FIG. 2B is a view illustrating a structure of a second cross-linking molecule used in  
Example [2] 1 of the method for forming an interlayer dielectric film of the first embodiment.

Page 20 continuing on page 21, line 24

92 FIGS. [13A] 12A through [13C] 12C are views illustrating steps of a method for forming  
an interconnection of the third embodiment.

Page 21, line 2

93 FIGS. [14A] 13A and [14B] 13B are views illustrating steps of the method for forming an  
interconnection of the third embodiment.